

Semiconductor Equipment Corporation

Dicing Tape

For almost 30 years Semiconductor Equipment Corporation has set the standard for high quality dicing tape.

Tapes are selected for your application based on die size and blade thickness. Small die and hard to cut materials require higher tackiness, while larger die call for lower tackiness. Thicker blades require thicker tape.

For additional information, please contact our Tape Specialist at (805) 529-2293 or sales@semicorp.com.

Standard Dicing Tape

SEC's most popular economical electronic grade dicing tape.



Blue Low Tack Rolls P/N 18733
Blue Medium Tack Rolls P/N 18074
Thickness 75 um / .003"
Length 200 M / 660'



Thick Clear Low Rolls P/N 24353
Thick Clear Medium Rolls P/N 24374
Thickness 120 um / .0047"
Length 100 M / 330'



Clear Low Tack Rolls P/N 19161
Thickness 100 um / .004"
Length 100 M & 200 M / 330' & 660'



Squares
All the above tapes are available in precut squares mounted on release paper. Standard sizes are 5.75" and 7.50". Custom sizes are available.



Inkjet Cover Tape
Blue tape in widths and adhesion levels designed for Inkjet cover tape.

Revalpha Heat Release



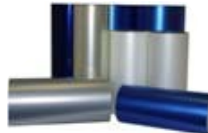
Excellent for high temperature applications. Available in single and double sided. Polyester film, acrylic adhesive, PET Liner



UV Curable Dicing Tape

A very high adhesive strength secures wafers firmly during dicing, while allowing for easy removal after exposure.

- P/N 24339 DU-300 Super High Tack, PVC, 85 um thick**
our most popular UV tape
- P/N 24351 NBD-5170K Super High Tack 170 um thick**
for dicing BGA & ceramic
- P/N 25551 DU-2187G Super High Tack 88 um thick**
for metalized wafers
- P/N 25587 NBD-3190K 193 um thick** *for glass dicing*
- P/N 25822 NBD-7163K 160 um thick** *for green package*
- P/N 25862 WS-02T Medium Tack 88 um thick**
- P/N 26115 DU-2285KS Low Tack 85um thick Anti-ESD**
- P/N 26120 DU-2385KS Low Tack 85 um thick Anti-ESD**
For metalized wafers



High Purity Pressure Sensitive Expandable Tape with Liner

Low ionic impurities and adhesion stability make this the perfect tape for your clean room application.

- P/N 24202 V8LR Low Tack 75 um thick** medium chip size
- P/N 24205 V8TR Low Tack 75 um thick** stable over time
- P/N 25213 V8SR Medium Tack, 70 um thick** most popular
- P/N 24211 VD15R High Tack 145 um thick** small chip size

Backgrinding Tape



Low contamination, consistent thickness accuracy, high acid resistance and effective protection during wet processes. UV and Anti-ESD products available.



Aquabond Adhesives

A family of unique, water soluble adhesives to mount items that require extra firm mounting, for dicing, grinding and polishing.

Semiconductor Equipment Corporation

P.O. Box 8079 5154 Goldman Avenue Moorpark, CA 93020
Phone: 805-529-2293 Fax: 805-529-2193
www.semicorp.com sales@semicorp.com